



## TSMC and ANSYS Enable Automotive Reliability Solutions

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PITTSBURGH, Sept. 14, 2017 /PRNewswire/ -- Customers of [TSMC](#) and [ANSYS](#) (NASDAQ: ANSS) can now accelerate the production of innovative automotive features through a new Automotive Reliability Solution Guide. The guide empowers customers to develop more efficient and robust chips for the next generation of smart automobiles, based on TSMC and ANSYS collaboration in ANSYS® RedHawk™, ANSYS® RedHawk-CTA™, ANSYS® Totem™ and ANSYS® Pathfinder-Static™ reliability solutions.

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Reliability is critical for cutting-edge automotive platforms used in advanced driver assistance systems, infotainment controls and autonomous driving. ANSYS and TSMC collaborated on the first-of-its-kind guide, incorporating various reliability capabilities in one place to support customers' IP, chip and package development for automotive applications in TSMC's 16-nanometer FinFET Compact Technology (16FFC) process and Automotive Design Enablement Platform (ADEP).

The Automotive Reliability Solution Guide outlines the various methodologies to simulate, debug and optimize electronic chips that customers can follow to perform electromigration, thermal and electrostatic discharge analysis. It enables customers to meet reliability requirements for automotive applications — empowering them to develop more robust and efficient chips in less time.

"The Automotive Reliability Solution Guide is built upon existing TSMC and ANSYS collaboration," said Suk Lee, senior director, design infrastructure marketing division at TSMC. "It serves as a jump-start for customers addressing reliability to improve design robustness for intellectual property, SoC and package design."

"As the automotive industry advances, demand increases for smart vehicles with innovative safety, comfort and entertainment functions," said John Lee, general manager at ANSYS. "The Automotive Reliability Solution Guide enables mutual customers to develop chips and packages that safely meet the level of sophistication and computing power needed for these products."

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